



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16842Generic Copy

Issue Date: 01-Jun-2012**TITLE:** Change of testing/packaging site for LC898300XA-MH**PROPOSED FIRST SHIP DATE:** 01-Sep-2012**AFFECTED CHANGE CATEGORY(S):** Test/Packing site Location Change**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Hironori.Terazawa@onsemi.com

SAMPLES: Contact your local ON Semiconductor Sales Office or Hironori.Terazawa@onsemi.com**ADDITIONAL RELIABILITY DATA:** N/A

Contact your local ON Semiconductor Sales Office or Hironori.Terazawa@onsemi.com

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

Test/Packing site Transfer from Sanyo Semiconductor (Thailand) to foundry.

Current

Testing site: Sanyo semiconductor Thailand

After

Test site: Yoshikawa Kogyo Co., Ltd.

Packing site: Taihei Electronics Co., Ltd.

* see appendix for more information

**ProcessFlowChart**

The reason is current Test site was closed due to damage resulting from the flood.



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VALIDATION DATA SUMMARY:

For qualification of the new test location, the following tests were successfully completed:

Gage Repeatability & Reproducibility – 20 pcs and 30X test contacts – All data passes error requirements for machine capability

Shmoo Plot – 4 pcs – All data passes requirements

Yield Correlations – All data passes requirements

ELECTRICAL CHARACTERISTIC SUMMARY:

No change to the device data sheets is being made. All parametric performance and limits remain the same.

CHANGED PART IDENTIFICATION:

No change to current part marking will occur. Marking traceability codes will be able to identify test site die source.

List of affected General Parts:

LC898300XA-MH